

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): An optical semiconductor module comprising:

light emitting means for emitting signal light;

optical transmitting means for transmitting said signal light surrounded by a clad layer;

light monitoring means for receiving forward light through said clad layer directly, which
is emitted from said light emitting means, provided on said clad layer; and

support means for supporting said light emitting means and said optical transmitting
means, and

reflecting means disposed between said optical waveguide and said support means for
reflecting leakage light of said signal light that is not coupled to said optical waveguide;

wherein said forward light is a portion of leakage light that is not coupled to said optical
transmitting means, and

wherein said optical transmitting means is an optical waveguide.
2. (previously presented): The optical semiconductor module as claimed in claim 1,
wherein said light monitoring means is provided on the opposite side of said clad layer from said
support means.

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Claims 3-5 (canceled).

6. (currently amended): The optical semiconductor module as claimed in claim 15, wherein said light monitoring means receives leakage light reflected by said reflecting means.

7. (currently amended): The optical semiconductor module as claimed in claim 13, wherein said optical transmitting means is an optical fiber.

8. (original): The optical semiconductor module as claimed in claim 7, further comprising positioning means for positioning said optical fiber so that said signal light emitted from said light emitting means can be optically coupled to said optical fiber.

9. (original): The optical semiconductor module as claimed in claim 7, wherein said light monitoring means is disposed so that it cannot contact said optical fiber.

10. (original): The optical semiconductor module as claimed in claim 1, wherein a current generated by said light monitoring means is used to control said signal light output from said light emitting means.

Claims 11-25 (canceled).

26. (currently amended): An optical semiconductor module comprising:
a light emitting element that emits signal light;
an optical waveguide that transmits said signal light surrounded by a clad layer;
a light monitor that receives forward light through said clad layer directly, provided on
said clad layer, which is emitted from said light emitting element; ~~and~~
a substrate for supporting said light monitor and said optical waveguide, and
a reflection film disposed between said optical waveguide and said substrate for
reflecting leakage light of said signal light that is not coupled to said optical waveguide..

27. (previously presented): The optical semiconductor module as claimed in claim 26,
wherein said light monitor is provided on the opposite side of said clad layer from said substrate.

28. (original): The optical semiconductor module as claimed in claim 26, wherein said
forward light is a portion of leakage light that is not coupled to said optical waveguide.

Claim 29 (canceled).

30. (original): The optical semiconductor module as claimed in claim ~~26~~²⁹, wherein said
light monitor receives leakage light reflected by said reflection film.

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31. (original): The optical semiconductor module as claimed in claim 26, wherein a current generated by said light monitor is used to control the signal light output of said light emitting element.

Claims 32-50 (canceled).